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CLAIMS 1-54 ARE CANCELED.

55. (currently amended) A method for burn-in testing a semiconductor die having a pad comprising:

providing a fixture for establishing electrical contact between the die and a burn-in oven, the fixture comprising a plate for receiving the die, an external lead on the plate, a cover configured for attachment to the plate, and a film comprising a bump for electrically contacting the pad and a conductive trace in electrical communication with the bump and the external lead;

placing the die face up on the plate and the film on the die with the bump on the pad; and

assembling the fixture by securing the cover to the plate with the film biased against the die and the bump in electrical contact with the pad; and

placing the external lead in electrical contact with the burn-in oven.

56. (previously presented) The method of claim 55 wherein the providing step comprises providing the fixture with a plurality of external leads and the film with a plurality of bumps and a plurality of conductive traces in electrical communication with the bumps.

57. (previously presented) The method of claim 55 wherein the providing step comprises providing the fixture with a compressible member and the assembling step is performed with the compressible member biasing the film against the die.

58. (previously presented) The method of claim 55 wherein the providing step comprises providing the fixture with a cavity on the plate for the die.

59. (previously presented) The method of claim 55 wherein the providing step comprises providing the fixture with a clamp and the assembling step comprises securing the cover to the plate with the clamp.

60. (previously presented) The method of claim 55 wherein the pad comprises a bondpad.

61. (previously presented) A method for burn-in testing a semiconductor die having a plurality of pads comprising:

providing a fixture for establishing electrical contact between the die and a burn-in oven, the fixture comprising a plate having a plurality of external leads, a cover, a compressible member and a film comprising a plurality of bumps in electrical communication with the external leads;

placing the die face up on the plate and the film on the die with the bumps on the pads;

assembling the fixture by securing the cover and the compressible member to the plate and biasing the film against the die; and

placing the external leads in electrical contact with the burn-in oven.

62. (previously presented) The method of claim 61 wherein the pads comprise bond pads.

63. (previously presented) The method of claim 61 wherein the film comprises a plurality of conductive traces configured to establish electrical communication between the bumps and the external leads.

64. (previously presented) The method of claim 61 wherein the external leads comprise pins in a dual in line (DIP) configuration.

65. (previously presented) The method of claim 61 wherein the external leads comprise pins in a quad flat pack (QFP) configuration.

66. (previously presented) The method of claim 61 wherein the compressible member comprises an elastomeric strip.

67. (currently amended) A method for burn-in testing a semiconductor die having a pad comprising:

providing a fixture for establishing electrical contact between the die and a burn-in oven, the fixture comprising a plate, a contact on the plate, and an external lead on the plate in electrical communication with the contact;

providing the fixture with a die contact member comprising a plastic film, a first bump on the plastic film for electrically contacting the pad, a conductive trace on the plastic film in electrical communication with the first bump, and a second bump on the plastic film in electrical communication with the conductive trace;

assembling the fixture with the die on the plate and the plastic film biased against the die with the first bump in contact with the pad and the second bump in contact with the contact; and

placing the external lead in electrical contact with the burn-in oven.

68. (previously presented) The method of claim 67 wherein the pad comprises a bondpad.

69. (previously presented) The method of claim 67 wherein the providing the fixture step comprises providing the fixture with a compressible member configured to bias

the plastic film against the die during the assembling step.

70. (previously presented) The method of claim 67 wherein the plastic film comprises polyamide.

71. (previously presented) The method of claim 67 wherein the second bump is bonded to the contact.

72. (currently amended) A method for burn-in testing a semiconductor die having a pad comprising:

providing a fixture for establishing electrical contact between the die and a burn-in oven, the fixture comprising a plate, an external lead on the plate, a cover and a compressible member configured for attachment to the plate, and a film comprising a bump for electrically contacting the pad and a conductive trace in electrical communication with the bump and the external lead;

assembling the fixture by placing the die on the plate, the film on the die, the compressible member on the film and then attaching the cover to the plate with the compressible member biasing the film against the die with the bump in electrical contact with the pad; and

placing the external lead in electrical contact with the burn-in oven.

73. (previously presented) The method of claim 72 wherein the fixture comprises a plurality of external leads and the film comprises a plurality of bumps and a plurality of conductive traces in electrical communication with the bumps.

74. (previously presented) The method of claim 72 the film comprises plastic.

75. (previously presented) The method of claim 72 wherein the pad comprises a bondpad.